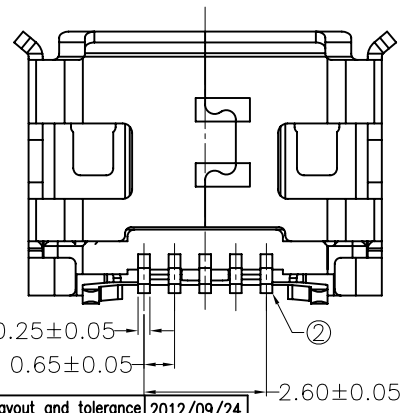
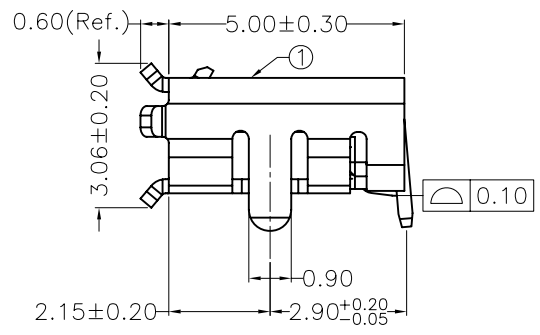
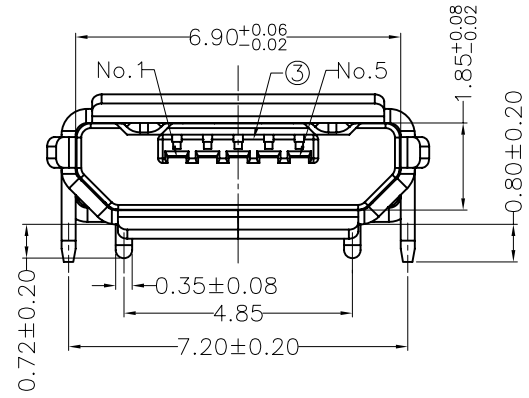
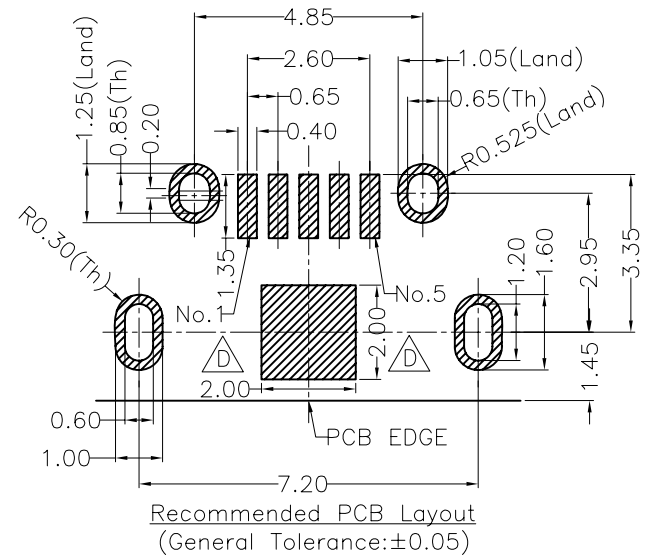
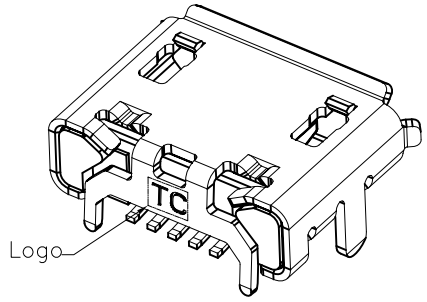
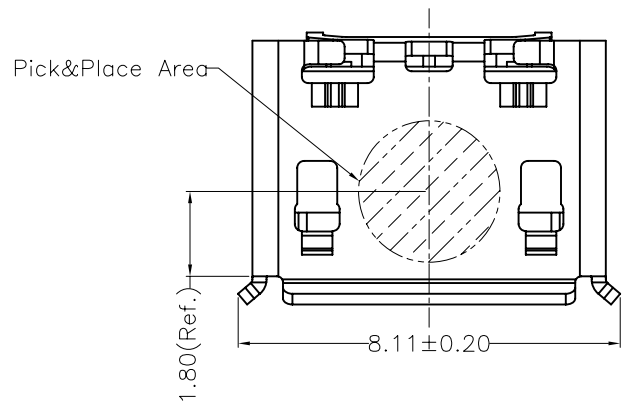


1 2 3 4 5 6 7 8 9 10

A  
B  
C  
D  
E  
F

THE PART MEETS TECONN "GP001" COMPLIANCE


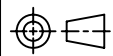


A4A0506-X-XX-R  
 LOGO  
 Mating Area plating  
 A:With "TC" LOGO,  
 D:Without LOGO,  
 01: Au 1u"Min.  
 03: Au 3u"Min.  
 05: Au 5u"Min.  
 10: Au 10u"Min.  
 15: Au 15u"Min.  
 30: Au 30u"Min.

Item	Title	Material	Dispose	Remark
1	Shell	Stainless Steel	Ni 30u"(min.)	t=0.30
2	Terminal	Copper Alloy	Mating Area:See P/N Solder Tails:G/F	t=0.15
3	InsertMolding	LCP	UL94V-0	Black

- 1.Contact Resistance:30mOHM Max.;
- 2.Dielectric Withstanding Voltage:100V AC For 1 Minute;
- 3.Insulation Resistance:1000M OHM Min.;
- 4.Mating And Unmating Force:  
Mating Force:35N Max/Unmating Force:8N Min;
- 5.Durability:10000 Cycles;

D	TE2012-xxxx	Modify PCB layout and tolerance	2012/09/24
C	TE2011-0044	Modify PCB Layout	2011/02/14
B	TE2010-729	Shell Plating Tin to Ni	2010/09/07
A	TE2010-230	New Drawing	2010/02/23
REV	ECN NO	DESCRIPTION	DATE

X. ± 0.35	APPD:	TITLE:	 泰康电子 TECONN
.X ± 0.25	CHKD:	Micro B Rec./Shell Dip	
.XX ± 0.15	DR:	Kevin Han	
.XXX ± 0.10			
X' ± 2'		PART NO:	A4A0506-X-XX-R
.X' ± 1.5'		DWG NO:	C-A4A0506-X-XX-R
	UNITS:	SCALE:	CUSTOMER DRAWING
	mm	6 : 1	SHEET:10F1
			REV: D

1 2 3 4 5 6 7 8 9 10